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(71) Applicant: **CABOT MICROELECTRONICS CORPORATION** [US/US]; Legal Department, 870 North Commons Drive, Aurora, Illinois 60504 (US).

(72) Inventors: **KELEHER, Jason**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **WOODLAND, Daniel**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **DE REGE THESAURO, Francis**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **MEDSKER, Robert**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US). **AGGIO, Jason**; c/o Legal Department, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US).

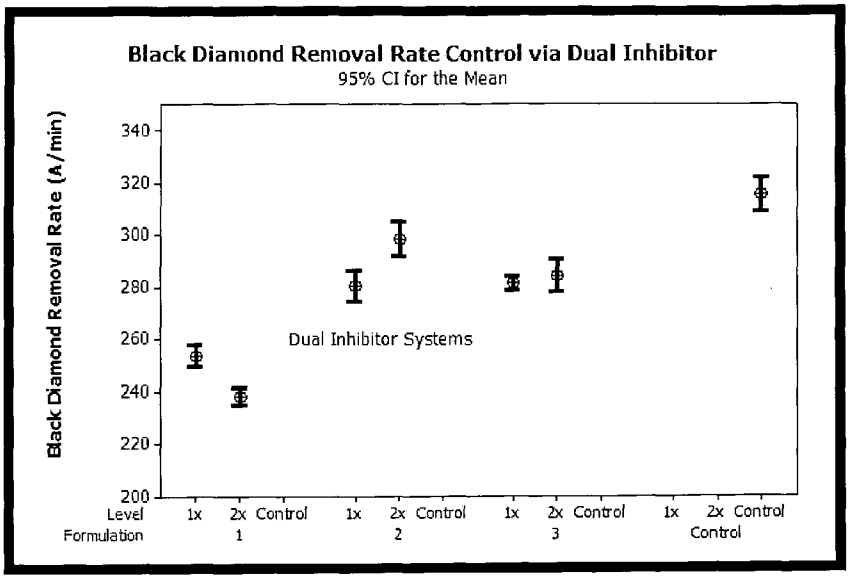
(74) Agents: **WESEMAN, Steven** et al.; Associate General Counsel, Intellectual Property, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, Illinois 60504 (US).

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[Continued on next page]

(54) Title: COMPOSITIONS AND METHODS FOR CMP OF LOW-K DIELECTRIC MATERIALS



(57) Abstract: The present invention provides a chemical-mechanical polishing (CMP) composition suitable for polishing low-k dielectric materials. The composition comprises a particulate abrasive material, at least one silicone-free nonionic surfactant comprising a hydrophilic portion and a lipophilic portion, at least one silicone-containing nonionic surfactant comprising a hydrophilic portion and a lipophilic portion, and an aqueous carrier therefor. A CMP method for polishing a low-k dielectric surface utilizing the composition is also disclosed.

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